



Final Product/Process Change Notification

Document #:FPCN23660XG

Issue Date:17 May 2023

Title of Change:	Additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu located in Aizu, Japan.
Proposed First Ship date:	15 Sep 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Polen.Pitpit@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	No change
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Aizu, Japan	None

Description and Purpose:

onsemi would like to inform its customers of additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu, Japan Manufacturing located in Aizu, Japan for the devices listed in this FPCN.

All products listed here will be dual sourced from its current wafer fab facility in onsemi wafer fab in Gresham, US and Aizu, Japan.

There is no change to the orderable part number.

There is no product marking change as a result of this change.

	Before Change Description	After Change Description
Wafer Fab Site	Gresham, US	Gresham, US and Aizu, Japan



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Reliability Data Summary:

QV DEVICE NAME: NCP12151BN65T1G

RMS: F77313, F78364

PACKAGE: PQFN-31

Test	Specification	Condition	Interval	Results (fail/pass)
HTOL	JESD22-A108	"Ta=125C, bias at Vcc= 1.2X Nominal (not to exceed Max rated), VIN=Max Op, device enabled and switching with PWM signal but no load on output. Power dissipation is minimal."	1008 hrs	0/240
HTSL	JESD22-A103	Ta= 150	1008 hrs	0/240
TC+PC	JESD22-A104	Temp = -65°C to +150°C	500 cyc	0/240
UHAST+PC	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs	0/240
SAT	as outlined in MSB17722C	12MSB17722C		0/30

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCP81145MNTBG	NCP1251BSN65T1G

Appendix A: Changed Products

PCN#: FPCN23660XG
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DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP81145MNTBG		NCP1251BSN65T1G		